Variant: 001

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TID #: TIDA-00808



TIDA-00808 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1		TIDA-00808	Any	Printed Circuit Board	
2	C2, C4	2	10uF	C5750X7S2A106M	TDK	CAP, CERM, 10 μF, 100 V, +/- 20%, X7S, 2220	2220
3	C3	1	1uF	C2012X7S2A105K125AB	TDK	CAP, CERM, 1 µF, 100 V, +/- 10%, X7S, 0805	0805
4	C5, C6	2	47uF	GRM32ER61C476KE15L	MuRata	CAP, CERM, 47 µF, 16 V, +/- 10%, X5R, 1210	1210
5	H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
6	H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
7	Q1	1	40 V	CMPT3906 LEAD FREE	Central Semiconductor	Transistor, PNP, 40 V, 0.2 A, SOT-23	SOT-23
8	R1, R2, R4	3	10k	CRCW060310K0JNEA	Vishay-Dale	RES, 10 k, 5%, 0.1 W, 0603	0603
9	R3	1	5.11k	CRCW06035K11FKEA	Vishay-Dale	RES, 5.11 k, 1%, 0.1 W, 0603	0603
10	R6	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
11	TP1, TP5	2	Red	5010	Keystone	Test Point, Multipurpose, Red, TH	Red Multipurpose
							Testpoint
12	TP2, TP3	2	Black	5011	Keystone	Test Point, Multipurpose, Black, TH	Black Multipurpose
							Testpoint
13	TP4	1	White	5012	Keystone	Test Point, Multipurpose, White, TH	White Multipurpose
							Testpoint
14	TP6, TP9	2	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature
							Testpoint
15	TP7, TP8	2	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature
							Testpoint
16	U1	1		LMZ36002RVQR	Texas Instruments	60V Input, 2.5V to 7.5V Output, 2A, RVQ0043A	RVQ0043A
17	C1	0	100uF	EEHZC1H101P	Panasonic	CAP, Polymer Hybrid, 100 µF, 50 V, +/- 20%, 28 ohm, 10x10 SMD	10x10
18	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
19	R5	0	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603

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